

# 型号: MT18Ex (C)

- MicroThin™为带有18 μm载体箔的超薄铜箔。  
MicroThin™ is ultra thin foil with 18 μm carrier foil.
- 适用于线宽/线距(L/S) =20/20~35/35的应用。  
Usable for fine pitch pattern L/S=20/20 - 35/35 formation.
- 适用于无芯封装工艺。  
Suitable for core-less process

## 用途/Application

- 半导体封装基板  
/Semiconductor Package
- 无芯封装基板  
/Core-less substrate

## 构成/Composition



## 生产地点/Production Site

- 日本 / Japan

## 代表性特性数据/Representative data

Model No.	μm	Area weight (g/m <sup>2</sup> )	Laminate side Rz (μm)	Tensile Strength (N/mm <sup>2</sup> )	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18Ex (C)	2	24	2	-	-	1.2
	3	33	2	-	-	1.2
	5	51	2	-	-	1.2

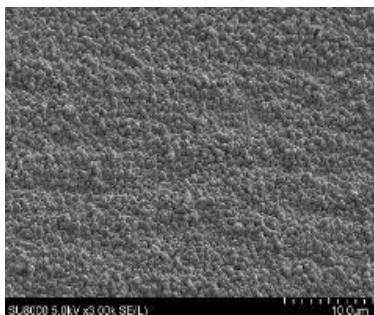
※上述列表为代表性数据，非保证数据。

This is representative data, not guaranteed.

※Peel Strength为增镀到35 μm厚度之后的测试值。

Evaluated after plated up to 35 μm.

处理面/Laminate side



阻剂面/Resist side

